L Number	Hits	Search Text	DB	Time stamp
-	659	(216/2).CCLS.	USPAT;	2003/05/01 09:46
			US-PGPUB	
-	141	((216/2).CCLS.) and (void or release or	USPAT;	2003/05/27 13:27
		cavity) and silicon adj dioxide	US-PGPUB	
-	70	((216/2).CCLS.) and (void or release or	USPAT;	2003/05/01 10:02
		cavity) and MEMS	US-PGPUB	
-	264	((216/2).CCLS.) and silicon adj dioxide	USPAT;	2003/04/29 09:27
			US-PGPUB	
-	517	mems and sacrificial and (cavity or void)	USPAT;	2003/05/30 09:02
			US-PGPUB	
-	7	mems and sacrificial and (cavity or void)	DERWENT	2003/04/29 12:54
-	33		DERWENT	2003/04/30 12:00
-	2	mems and sacrificial	JP0	2003/04/29 12:59
-	4	mems and (void or cavity)	JPO	2003/04/29 12:59
-	109		USPAT;	2003/04/29 14:25
		(substrate or silicon)).clm.	US-PGPUB	
	22	· · · · · · · · · · · · · · · · · · ·	DERWENT	2003/04/30 12:10
-	1	release and silicon and dioxide and (wafer	DERWENT	2003/04/30 12:08
		near3 bond\$3)		
-	4	1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1	DERWENT	2003/04/30 12:09
		and silicon and dioxide and (substrate		ļ
		near3 bond\$3)		
-	708	sacrificial and (wafer near3 bond\$3)	USPAT;	2003/04/30 12:11
			US-PGPUB	
-	366		USPAT;	2003/05/30 10:12
		(silicon adj dioxide) and (releas\$3 or	US-PGPUB	
		etch\$3)		
-	5	(sacrificial and (wafer near3 bond\$3) and	USPAT;	2003/04/30 12:14
		(silicon adj dioxide) and (releas\$3 or	US-PGPUB	
		etch\$3)).clm.		
-	195		USPAT;	2003/04/30 12:15
	_	mems)	US-PGPUB	
-	3	(("6417743") or ("6463339") or	USPAT;	2003/05/01 09:52
		("6348788")).PN.	US-PGPUB	
-	1	("6159385").PN.	USPAT;	2003/05/01 10:00
			US-PGPUB	
-	1	("6417743").PN.	USPAT;	2003/05/01 10:00
			US-PGPUB	
_	12		USPAT;	2003/05/01 10:02
		cavity) and MEM	US-PGPUB	00000105104
_	79	((1 / -)	USPAT;	2003/05/01 10:03
	0.40	cavity) and (MEM or "MEM's")	US-PGPUB	2002/05/07 12 40
_	240		USPAT;	2003/05/27 13:40
ļ	0.1.5	cavity or well) and silicon adj dioxide	US-PGPUB	00002/05/07 14 00
-	215	((216/2).CCLS.) and (micromechanical or	USPAT;	2003/05/27 14:03
		MEMS or micro-electromechanical or	US-PGPUB	
	1000	microelectromechanical)	110000	00002/05/00 10 00
-	1009	',	USPAT;	2003/05/30 10:03
		micro-electromechanical or	US-PGPUB	
		microelectromechanical or		
	1020	micro-mechanical).ti.	Hann	2002/05/27 14 07
-	1039	(micromechanical or MEMS or micro-electromechanical or	USPAT;	2003/05/27 14:07
			US-PGPUB	
		microelectromechanical		
		micro-electro-mechanical or		
	074	micro-mechanical).ti.	110538	2002/05/20 10 07
-	8 / 4	(micromechanical or MEMS or micro-electromechanical or	USPAT;	2003/05/30 10:07
			US-PGPUB	
		microelectromechanical		
		micro-electro-mechanical or		
		micro-mechanical).ti. and (cavity or void		
	4.0	or recess or well)	II.O.D.A.m.	1 2003/05/20 00 02
-	4.9	(mems and (cavity or void or recess)).ab.	USPAT;	2003/05/30 09:03
	105	(migrost rugtures or MDMC) to and (migrost rugtures)	US-PGPUB	2002/05/20 00 :0
-	195	(microstructures or MEMS).ti. and (void or	USPAT;	2003/05/30 09:48
	_	cavity or recess)	US-PGPUB	2002/05/20 00 11
-	9	("5198390" "5314572" "5364497"	USPAT	2003/05/30 09:41
		"5543013" "5637539" "5747353"	1	
	305	"5824177" "5879963" "6020215").PN.	HCDAM -	2002/05/20 00 50
-	325		USPAT;	2003/05/30 09:52
		or dioxide) same cavity	US-PGPUB	·

_	59	method same suspended same structure? same	USPAT;	2003/05/30 09:54
		silicon	US-PGPUB	
_	1269	(micromechanical or MEMS or	USPAT;	2003/05/30 10:04
		microstructure? or micro-electromechanical	US-PGPUB	
		or microelectromechanical or		
		micro-mechanical).ti.		
1	89		JPO	2003/05/30 10:04
-	89	(micromechanical or MEMS or	JPO	2003/03/30 10:04
		microstructure? or micro-electromechanical		
		or microelectromechanical or		
		micro-mechanical).ti.		
_	149	(micromechanical or MEMS or	USPAT;	2003/05/30 10:09
		micro-electromechanical or	US-PGPUB	1
		microelectromechanical		
		micro-electro-mechanical or		
	1	micro-mechanical or microstructures or	İ	
		microstructure or suspended).ti. and		
				ļ
		(cavity or void or recess or well) and		
		MEMS and wafer and silicon		
-	701	, , , , , , , , , , , , , , , , , , , ,	USPAT;	2003/05/30 10:37
		etch\$3) and (micromechanical or mems or	US-PGPUB	
		microstructure? or micro-mechanical)		
-	4		USPAT	2003/05/30 10:34
		"5658698").PN.		
_	82	(sealed adj cavity) same (wafer or	USPAT;	2003/06/02 17:09
		substrate) same (\$20xide or dielectric or	US-PGPUB	[2000,00,02 1,.09]
			US FOFUD	
	0.35	insulat\$3)	HCDAM -	2003/06/02 16:08
_	235		USPAT;	2003/06/02 16:08
		(structure or mechanical or etch\$3)	US-PGPUB	
-	1	"6465355"	DERWENT	2003/06/02 16:02
-	1	2003-310327.NRAN.	DERWENT	2003/06/02 16:02
-	2637	cavity and suspended and (structure or	USPAT;	2003/06/02 16:24
		mechanical or micromachin\$3) and etch\$3	US-PGPUB	
_	62	(cavity and micromachin\$3).ab. and etch\$3	USPAT;	2003/06/02 16:23
		,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,	US-PGPUB	
_	3	(void and micromachin\$3).ab. and etch\$3	USPAT;	2003/06/02 16:23
		(vota ana mioromaonini, o) iazi ana ocompo	US-PGPUB	
	365	void and micromachin\$3 and etch\$3	USPAT;	2003/06/02 16:42
-	303	Void and micromachings and ecches	US-PGPUB	2003/00/02 10:42
			i	2002/06/02 16:25
-	54		USPAT;	2003/06/02 16:25
	_	mechanical or micromachin\$3)).ab.	US-PGPUB	
_	5	svoronos.in.	USPAT;	2003/06/02 16:43
			US-PGPUB	
_	213	(harris adj richard).in.	USPAT;	2003/06/02 16:47
			US-PGPUB	
-	35	(kretschmann).in.	USPAT;	2003/06/02 16:47
		·	US-PGPUB	Ţ
_	4163	MEMS and (remov\$3 or etch\$3)	USPAT;	2003/06/02 17:00
	,		US-PGPUB	= 100,00,02 100
_	111	(mems and (void or cavity) and (substrate	USPAT;	2003/06/02 17:00
	1 111	or silicon)).clm.	i i	2003/00/02 17:00
	202	, ,	US-PGPUB	2002/06/02 17 :-
-	393	(438/48).CCLS.	USPAT;	2003/06/02 17:45
			US-PGPUB	1
] -	79	((438/48).CCLS.) and (cavity or void or	USPAT;	2003/06/02 17:14
		recess)	US-PGPUB	
-	302	(438/52).CCLS.	USPAT;	2003/06/02 18:03
			US-PGPUB	
-	186	(438/51).CCLS.	USPAT;	2003/06/02 18:13
			US-PGPUB	
-	154	((438/51).CCLS.) not ((438/52).CCLS.)	USPAT;	2003/06/02 18:04
	101	((150/02/,0000.)	US-PGPUB	1000,00,02 10.04
_	152	(438/456).CCLS.	USPAT;	2003/06/02 18:14
	154	(100/100).0000.		2003/00/02 10:14
		(430 /4EE) CCI C	US-PGPUB	2002/06/02 10 15
-	591	(438/455).CCLS.	USPAT;	2003/06/02 18:15
			US-PGPUB	
-	548	((438/455).CCLS.) not ((438/456).CCLS.)	USPAT;	2003/06/02 18:16
			US-PGPUB	